TOSHIBA Intelligent Power Device Silicon Monolithic Power MOS Integrated Circuit

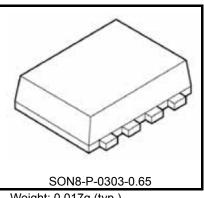
# **TPD7102F**

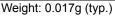
1 channel High-Side N channel Power MOSFET Gate Driver

TPD7102F is a 1channel high-side N channel power MOSFET gate driver. This IC contains a charge pump circuit, allowing easy configuration of a high-side switch for large-current applications.

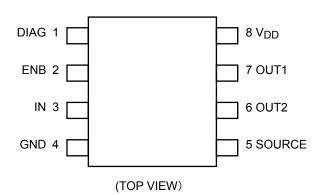
#### Features

- Charge pump circuit is built in
- The diagnosis function of the voltage between OUT1 and SOURCE is built in
- Housed in the PS-8 package and supplied in embossed carrier tape.

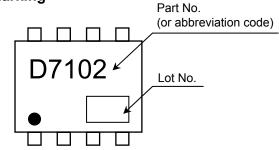




#### **Pin Assignment (top view)**



Marking



•Note:● on the lower left of the marking indicates Pin 1

\*Weekly code: (Three digits)



Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product.

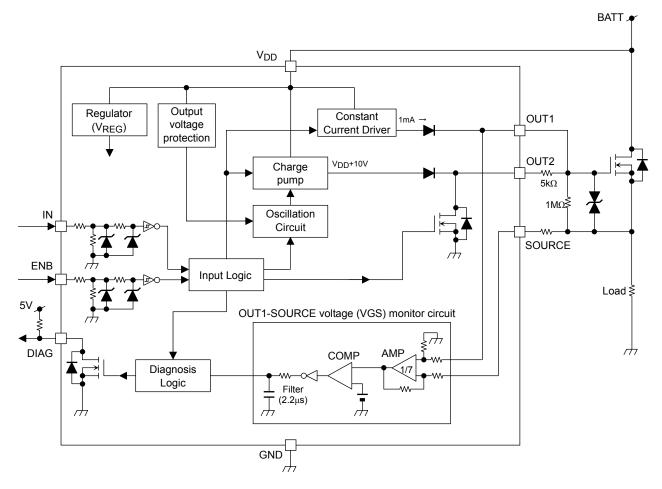
The RoHS is the Directive 2002/95/EC of the European Parliament and of the Council of 27 January 2003 on the restriction of the use of certain

Note: That because of its MOS structure, this product is sensitive to static electricity.

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#### Block Diagram / Application circuit

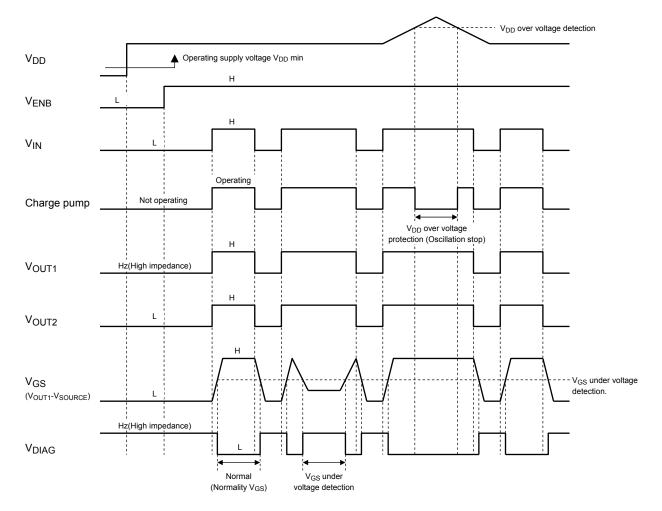


# <u>TOSHIBA</u>

#### **Pin Description**

Pin No.	Symbol	Function
1	DIAG	Diagnosis detection pin. N channel open drain.
2	ENB	Enable pin. The ENB pin has a pull-down resistor. When $V_{ENB}$ is L, OUT1 is Hz and OUT2 is L.
3	IN	Input pin. The IN pin has a pull-down resistor. When $V_{\text{IN}}$ and $V_{\text{ENB}}$ are H, OUT1 and OUT2 are H.
4	GND	Ground pin.
5	SOURCE	Source voltage of the external power MOSFET monitor pin.
6	OUT2	Output pin 2.
7	OUT1	Output pin 1.
8	V <sub>DD</sub>	Power supply pin.

#### **Timing Chart**



Note: IN and ENB apply H, after  $\mathsf{V}_{DD}$  applied operating supply voltage.

#### **Truth Table**

IN signal	ENB signal	Charge pump circuit	V <sub>OUT1</sub>	V <sub>OUT2</sub>	V <sub>GS</sub>	DIAG	Mode
L	L	Oscillation stop	Hz	L	V <sub>GS</sub> =H	Hz	
Н	L		Hz	L		Hz	
L	Н		Hz	L		Hz	
Н	Н	Oscillation	Н	Н		L	Normal
L	L	Oscillation stop	Hz	L	V <sub>GS</sub> =L	Hz	(V <sub>DD</sub> =7 to 18V)
Н	L		Hz	L		Hz	
L	Н		Hz	L		Hz	
Н	Н	Oscillation	Н	н		Hz	
L	L	Oscillation stop	Hz	L	V <sub>GS</sub> =H	Hz	
Н	L		Hz	L		Hz	
L	Н		Hz	L		Hz	
Н	Н		Н	Н		L	V <sub>DD</sub> over volatage
L	L		Hz	L	V <sub>GS</sub> =L	Hz	(V <sub>DD</sub> >18V)
Н	L		Hz	L		Hz	
L	Н		Hz	L		Hz	
Н	Н		Н	Н		Hz	

Note: V\_{GS}=H(V\_{GS}>V\_{GSUV}) / V\_{GS}=L(V\_{GS}\leq V\_{GSUV}) \quad {}^{\*}V\_{GS}=V\_{OUT1}-V\_{SOURCE} Note: Hz: High impedance

\* DIAG is L only when  $V_{IN}$  and  $V_{ENB}$  and  $V_{GS}$  are H.

Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	Remarks
Power supply voltage	DC	V <sub>DD(1)</sub>	-0.3 to 25	V	
	Pulse	V <sub>DD(2)</sub> 35 V t=400ms sing		t=400ms single pulse	
Input voltage		V <sub>IN</sub>	-0.3 to 6	V	
Diagnosis output voltage		V <sub>DIAG</sub>	-0.3 to 25	V	
Diagnosis output current		I <sub>DIAG</sub>	2	mA	
Output sink current(DC)		I <sub>OUT2</sub> (+)	5	mA	Sink current
SOURCE pin negative voltage		-V <sub>SOURCE</sub>	-7	V	t≤0.1μs, SOURCE pin 10kΩ connect
Power dissipation (Note 1-a)		P <sub>D(1)</sub>	0.7	W	
Power dissipation (Note 1-b)		P <sub>D(2)</sub>	0.35	W	
Operating temperature		T <sub>opr</sub>	-40 to 125	°C	
Junction temperature		Тj	150	°C	
Strage temperature		T <sub>stg</sub>	-55 to 150	°C	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

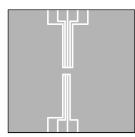
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### **Thermal Resistance**

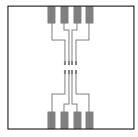
Characteristic	Symbol	Rating	Unit
Thermal resistance, junction to ambient	t R <sub>th (j–a)</sub>	178.6(Note 1-a)	°C/W
includi resistance, junction to amplent		357.2(Note 1-b)	0/10

Note 1:

(a)Glass epoxy board



Glass epoxy board Material: FR-4 25.4mm×25.4mm×0.8mm



(b)Glass epoxy board

Glass epoxy board Material: FR-4 25.4mm×25.4mm×0.8mm

### Electrical Characteristics (Unless otherwise specified, $T_j = -40$ to $125^{\circ}C$ , $V_{DD} = 7$ to 18V)

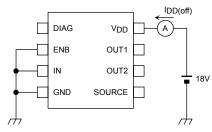
Characteristics	Symbol	Pin	Test Condition	Min	Тур.	Max	Unit	
Operating supply voltage (Charge pump circuit, Input logic, Diagnosis logic operate)	V <sub>DD(OPR)</sub>	V <sub>DD</sub>	-	7	12	18	V	
Supply current	I <sub>DD(off)</sub>	V <sub>DD</sub>	V <sub>DD</sub> = 18V, V <sub>IN</sub> =V <sub>ENB</sub> = 0V	-	0.35	2	mA	
	I <sub>DD(on)</sub>	V <sub>DD</sub>	V <sub>DD</sub> = 18V, V <sub>IN</sub> =V <sub>ENB</sub> = 5V	-	3	8	mA	
Input voltage	V <sub>INH</sub> IN, ENB		-	3.5	-	-	V	
input voltage	V <sub>INL</sub>	IIN, LIND	-	-	-	1.5	v	
Input current	I <sub>INH,</sub> I <sub>ENBH</sub>	IN, ENB	V <sub>IN</sub> =V <sub>ENB</sub> = 5V *Each pin current	-	50	200	- μΑ	
	I <sub>INIL,</sub> I <sub>ENBL</sub>		V <sub>IN</sub> =V <sub>ENB</sub> = 0V *Each pin current	-1	-	1		
Output voltage	V <sub>OUT1H</sub>	OUT1	$V_{DD}$ = 9 to 18V, $V_{IN}$ = $V_{ENB}$ =5V, $V_{SOURCE}$ = $V_{DD}$ , OUT1-SOURCE 1M $\Omega$	V <sub>DD</sub> -2.7	V <sub>DD</sub> -1	V <sub>DD</sub>	v	
Output voltage	V <sub>OUT2H</sub>	OUT2	$V_{DD}$ = 9 to 18V, $V_{IN}$ = $V_{ENB}$ =5V, $V_{SOURCE}$ = $V_{DD}$ , OUT2-SOURCE 1M $\Omega$	V <sub>DD</sub> + 6.0	V <sub>DD</sub> +10	V <sub>DD</sub> +12.5	v	
OUT2 sink DMOS ON-Resistance	R <sub>ONOUT2L</sub>	OUT2	$V_{DD}$ = 7 to 18V, $V_{IN}$ = $V_{ENB}$ = 0V, I <sub>OUT2</sub> =1mA	-	70	180	Ω	
OUT1 high level output current	IOH1	OUT1	V <sub>DD</sub> =9 to 18V, V <sub>IN</sub> =V <sub>ENB</sub> =5V	-	-1.0	-0.15	mA	
OUT1 output leakage current	IOL1	OUT1	V <sub>DD</sub> =9 to 18V, V <sub>IN</sub> =V <sub>ENB</sub> =0V	-1	-	-	μA	
OUT1 sink current	I <sub>OUT1+</sub>	OUT1	V <sub>OUT1</sub> =12V,V <sub>IN</sub> =V <sub>ENB</sub> =0V	-	5	20	μA	
OUT2 output current	IOH2	OUT2	V <sub>DD</sub> =9 to 18V, V <sub>IN</sub> =V <sub>ENB</sub> =5V, V <sub>OUT2</sub> =V <sub>DD</sub> +6V	-	-100	-30	μA	
Diagnosis output leakage current	IDIAGH	DIAG	$V_{DD}$ = 7 to 18V, $V_{IN}$ = $V_{ENB}$ =0V $V_{DIAG}$ = 5V	-	-	10	μA	
Diagnosis output voltage	VDIAGL	DIAG	V <sub>DD</sub> = 7 to 18V, V <sub>IN</sub> =V <sub>ENB</sub> =5V I <sub>DIAG</sub> = 1mA	-	-	0.4	v	
V <sub>GS</sub> under voltage detection (OUT1-SOURCE voltage)	GS under voltage detection VGSUV S		V <sub>DD</sub> = 9 to 18V, V <sub>IN</sub> =V <sub>ENB</sub> =5V	3.3	4.1	4.8	V	
V <sub>DD</sub> over voltage detection	V <sub>DDOV</sub>	V <sub>DD</sub>	-	18	22	25	V	
Quitabing time	t <sub>on</sub>			-	16	100		
Switching time	t <sub>off</sub>	IN→OUT1	Refer to Test circuit 7	-	2	10	μS	

Note: Typical condition is V\_DD=12V, T\_j=25°C.

Note: Sink current to this IC is expressed by "+", source current from this IC is expressed by "-".

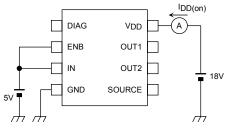
### Test circuit 1

Supply current I<sub>DD(off)</sub>



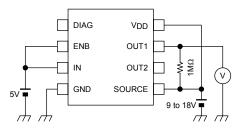
### Test circuit 2

Supply current I<sub>DD(on)</sub>



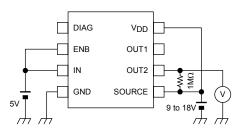
### Test circuit 3

Output voltage V<sub>OUT1H</sub>



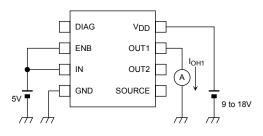
### Test circuit 4

Output voltage V<sub>OUT2H</sub>



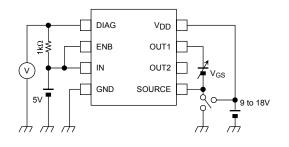
#### Test circuit 5

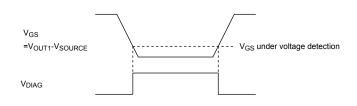
OUT1 high level output current IOH1



#### Test circuit 6

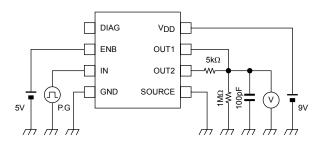
 $\mathsf{V}_{GS}$  under voltage detection

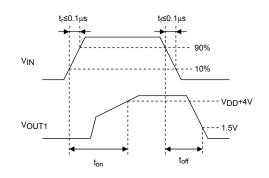


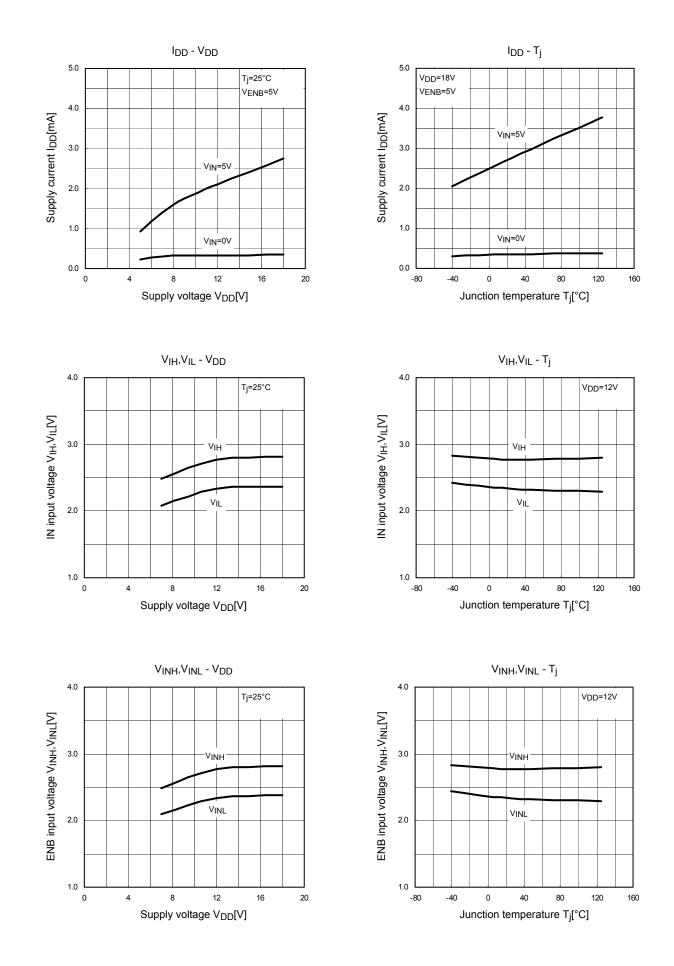


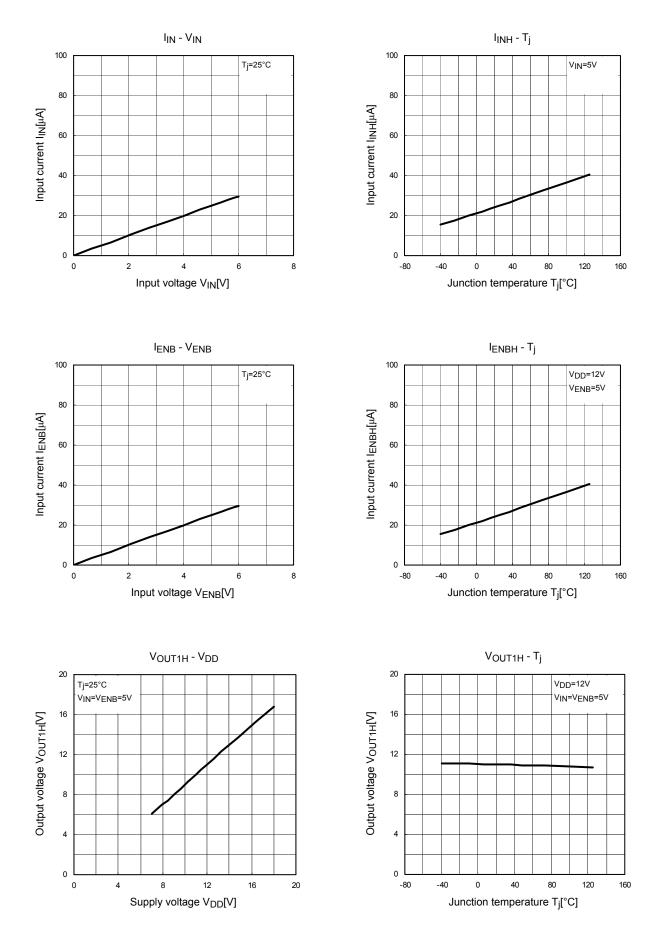
#### Test circuit 7

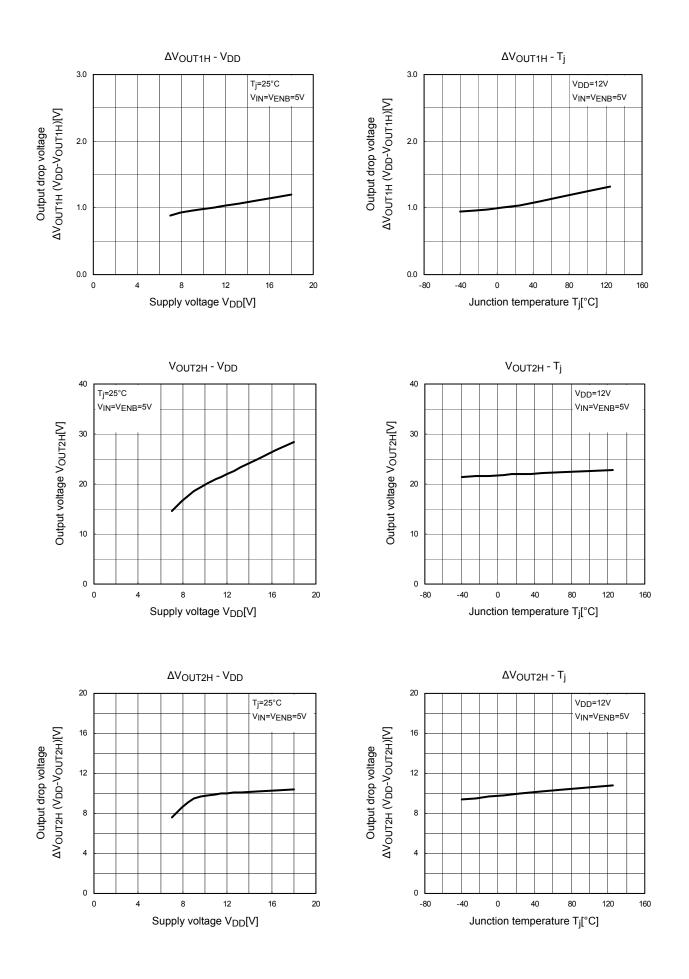
Switching time ton, toff

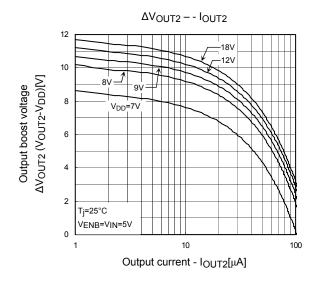


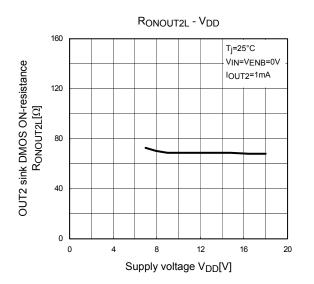


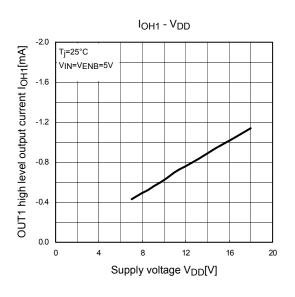


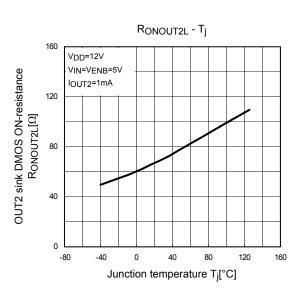


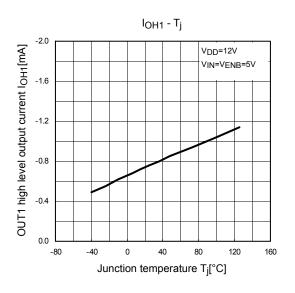












0.5

0.4

0.3

0.2

0.1

0.0

5.0

4.6

4.2

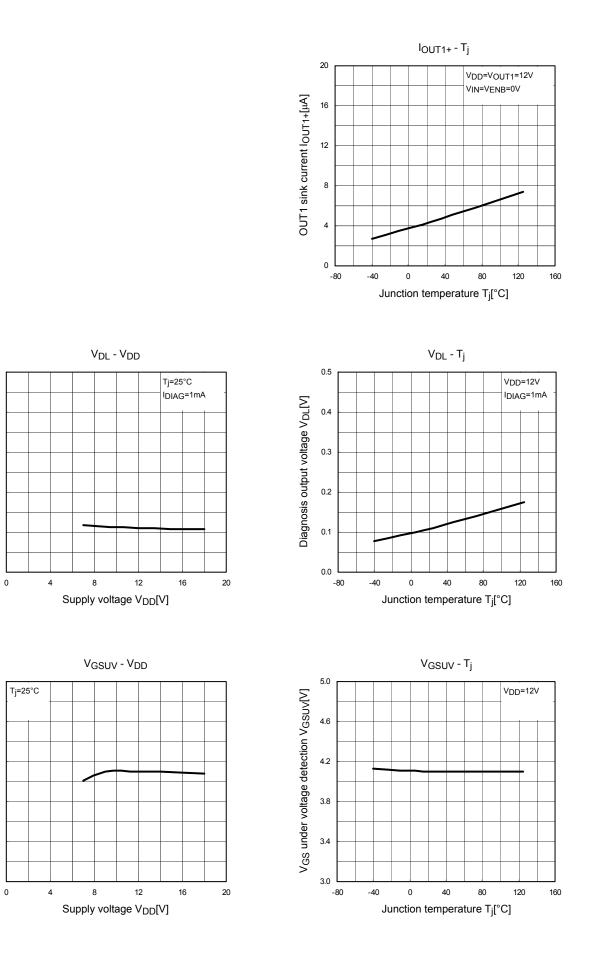
3.8

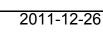
3.4

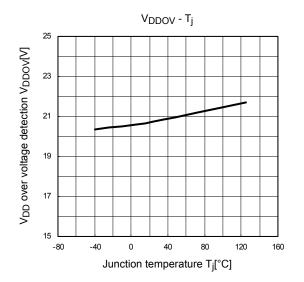
3.0

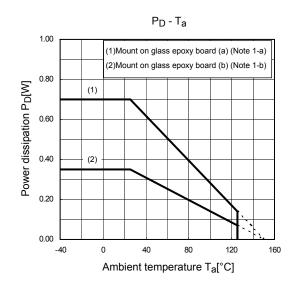
VGS under voltage detection VGSUV[V]

Diagnosis output voltage V<sub>DL</sub>[V]





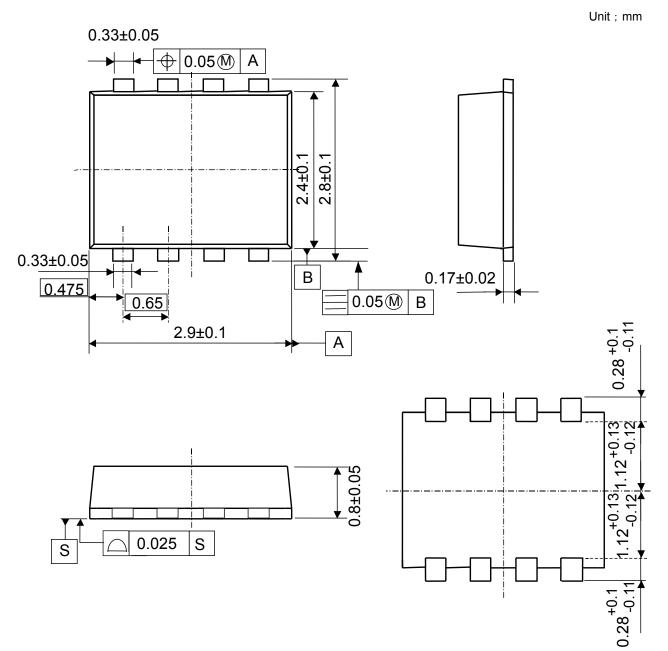




TPD7102F

#### Package Dimensions

SON8-P-0303-0.65



Weight : 0.017g(Typ.)

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